

Electronic Patent Application Fee Transmittal

Application Number:	10826985			
Filing Date:	19-Apr-2004			
Title of Invention:	Methods for forming protective layers on semiconductor device components so as to reduce or eliminate the occurrence of delamination thereof and cracking therein			
First Named Inventor/Applicant Name:	Shijian Luo			
Filer:	Brick Glenn Power/Sharley Thayne			
Attorney Docket Number:	2269-5565.1US (02-1124.01)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Filing a brief in support of an appeal	1402	1	510	510
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				510